

CMS Phase 2 Upgrades

New Tracker

- Radiation tolerant - high granularity - less material
- Tracks in hardware trigger (L1)
- Coverage up to $\eta \sim 4$

New Endcap Calorimeters

- Radiation tolerant - high granularity
- Investigate coverage up to $\eta \sim 4$

Barrel ECAL

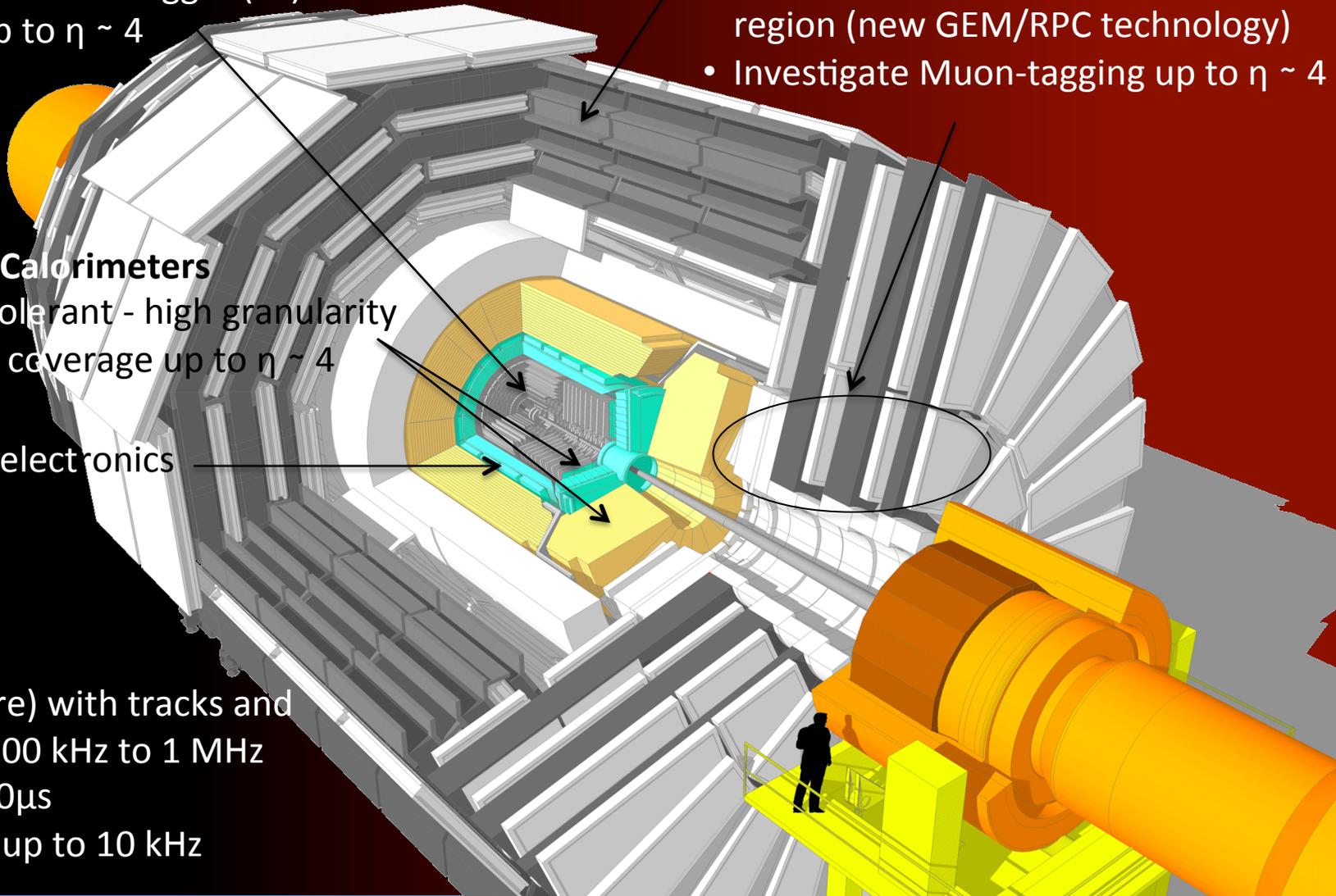
- Replace FE electronics

Trigger/DAQ

- L1 (hardware) with tracks and rate up ~ 500 kHz to 1 MHz
- Latency $\geq 10\mu\text{s}$
- HLT output up to 10 kHz

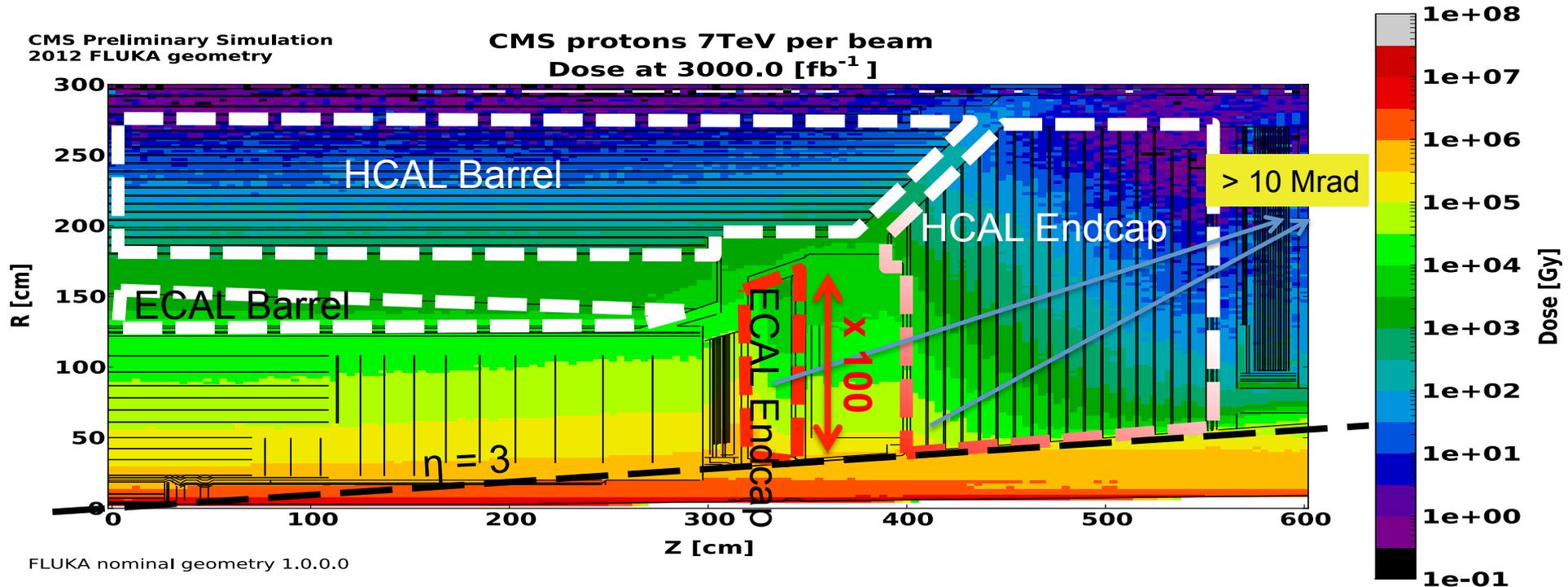
Muons

- Replace DT FE electronics
- Complete RPC coverage in forward region (new GEM/RPC technology)
- Investigate Muon-tagging up to $\eta \sim 4$



Radiation and pileup environment

- Radiation six times higher than nominal LHC design
- $5(7)E34 \text{ Hz/cm}^2 \rightarrow \sim 140 (200) \text{ collisions/bunch crossing}$



Longevity studies and simulation for $300 \text{ fb}^{-1}/\text{y} \rightarrow 3000 \text{ fb}^{-1} \text{ total}$

LHC long term schedule (Dec 2013)

CMS Technical Proposal end 2014
 CMS Technical Design Reports 2016-17

LHC schedule beyond LS1

Only EYETS (19 weeks) (no Linac4 connection during Run2)

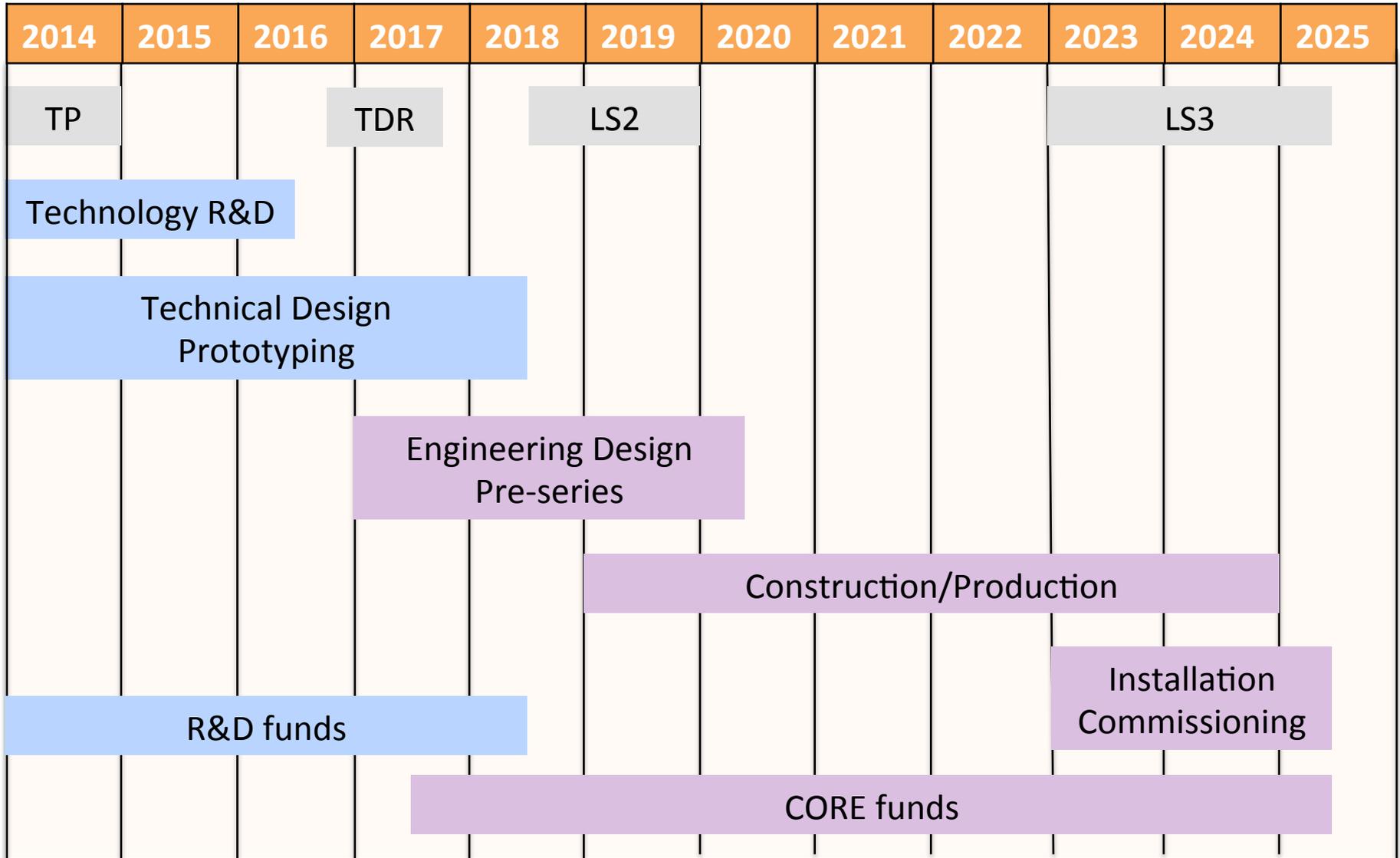
LS2 starting in 2018 (July) 18 months + 3months BC (Beam Commissioning)

LS3 LHC: starting in 2023 => 30 months + 3 BC
 injectors: in 2024 => 13 months + 3 BC



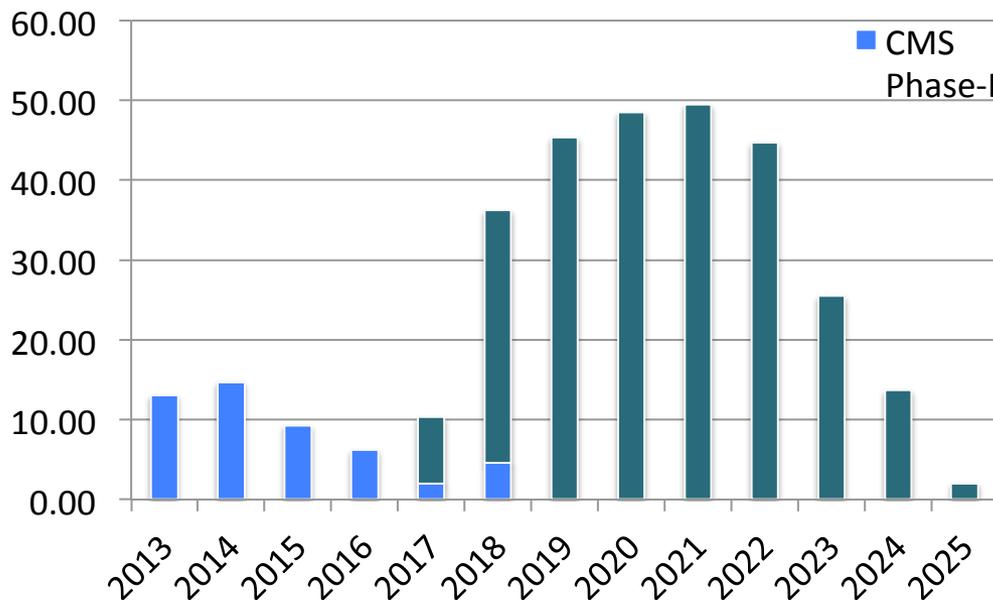
CMS steps for Phase 2 completion

based on Dec. 13 schedule



Phase 2 Upgrades Resource Profile

Phase 2 total estimate ~269 M CHF (October 2013):
 initial estimate to be reviewed for TP (2014) and TDRs (2016-17)

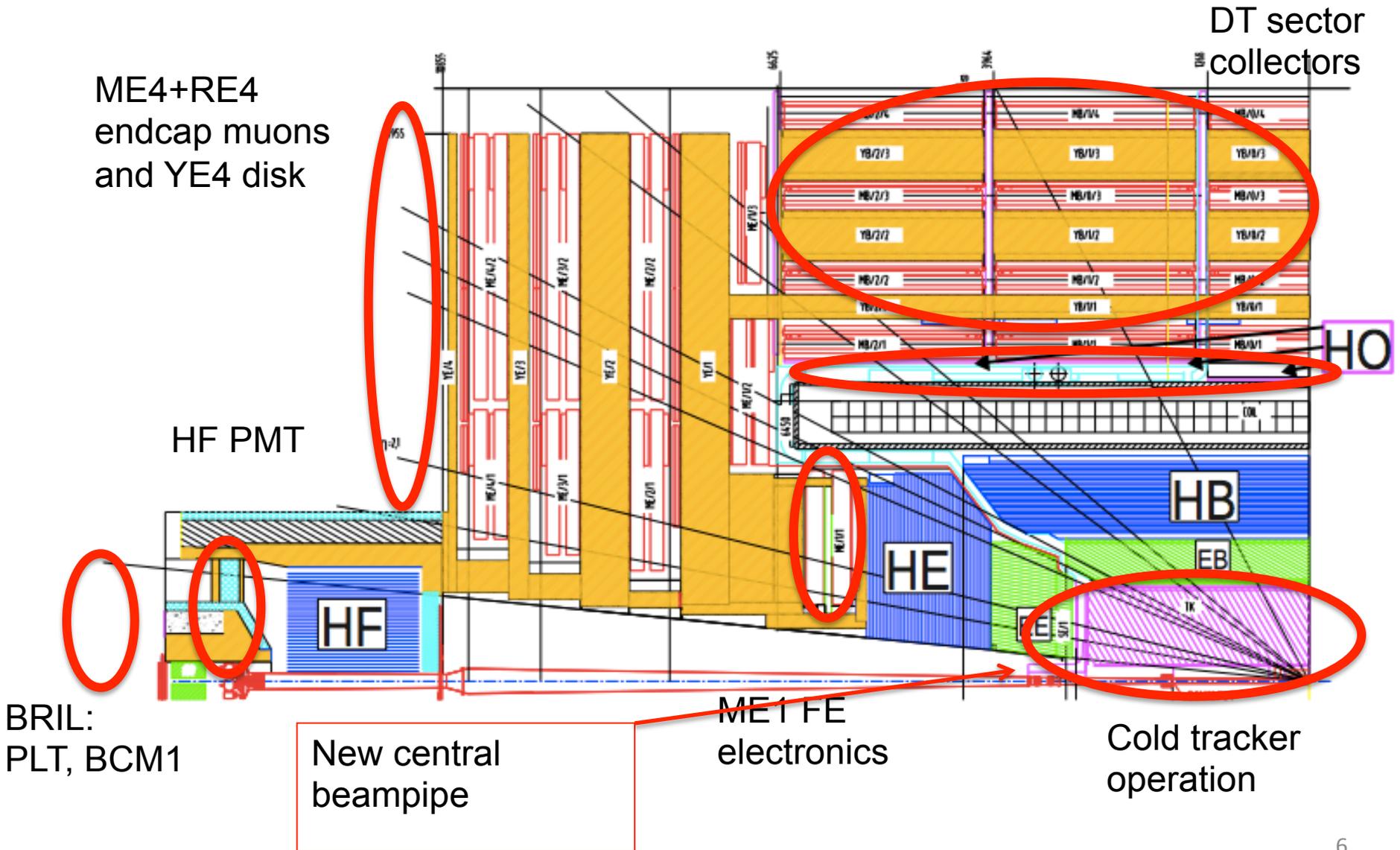


Summary of Phase 2 Costs		
Item	Sub-item	Estimated CORE Cost (MCHF 2013)
Tracker	Silicon Tracker	94
	Pixel Detector	34
	Total	127
Calorimeters	Endcap Calorimeter Upgrade: EM & HAD	67
	HF upgrade to 4-channels per PMT	2
	Total	69
Muon System	DT Electronics	7
	Endcap Muon System Upgrade	12
	High Eta Muon Tagging Station	6
Total	25	
Trigger System and Front-end Electronics	L1-Trigger	7
	EB Frontend Electronics	11
	Total	18
DAQ and HLT	DAQ system: Clock, Readout, Network	5
	HLT	6
	Total	11
Infrastructure and Common Systems	Shielding Changes for HL-LHC	6
	Tooling, rail systems, cranes for LS3 work	5
	Common Systems and Installation	9
Total	19	
Total		269

Table 3.1.1: Summary of CORE costs for the CMS Phase 2 Upgrade

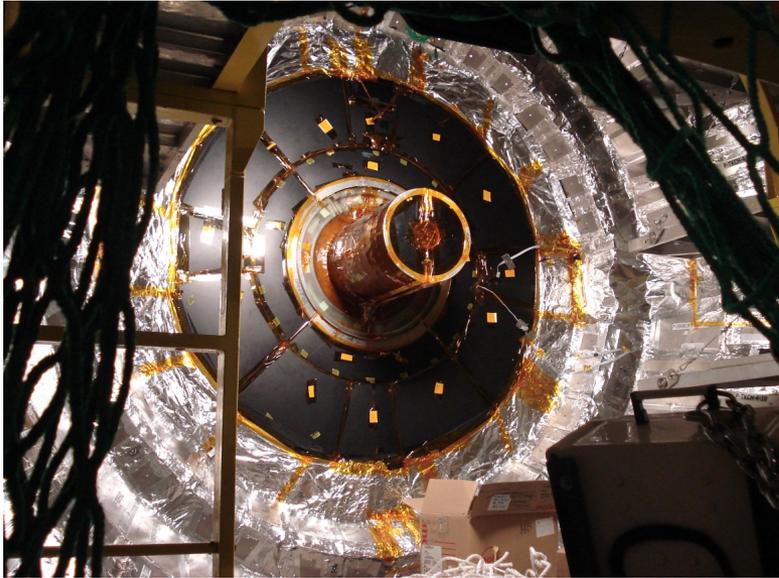
<https://cds.cern.ch/record/1605208/files/CERN-RRB-2013-124.pdf>

Detector activities in LS1 (2013-2014)

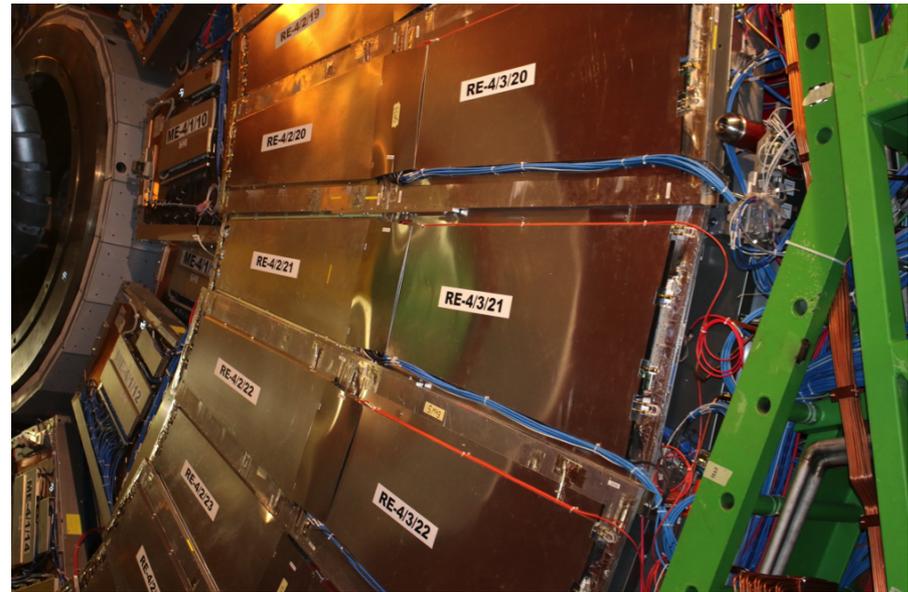


LS1: on track getting ready for Run 2

Tracker cold: tested -20°C (Strips), -25°C (Pixel) OK !!
Operation at tested -15°C

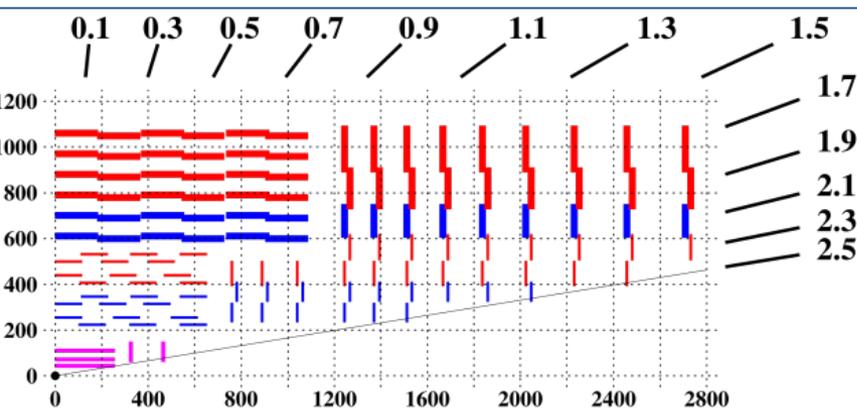


RE4 construction (144 new RPC)
and installation completed !!

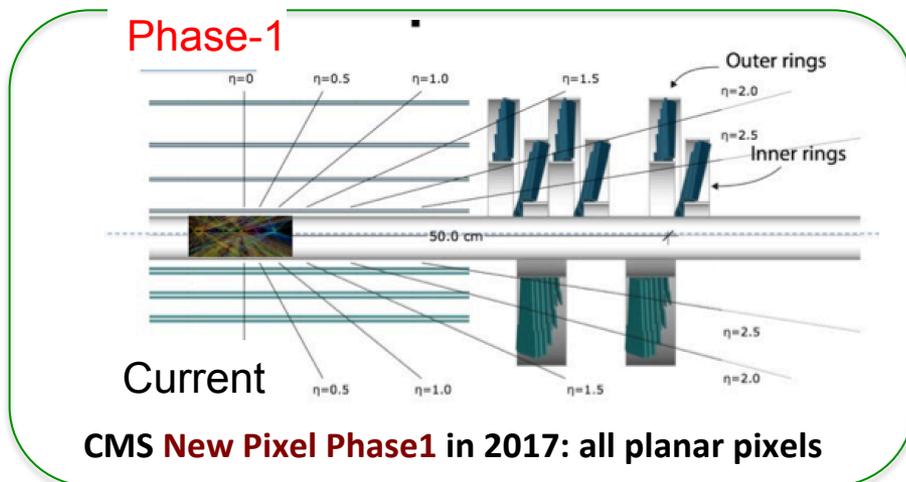


- DT sector collector OK
- New beampipe OK
- Radiation shielding ready soon
- L1 trigger in progress
- New pixel to be installed end 2016...

From Current to Phase2 Tracker



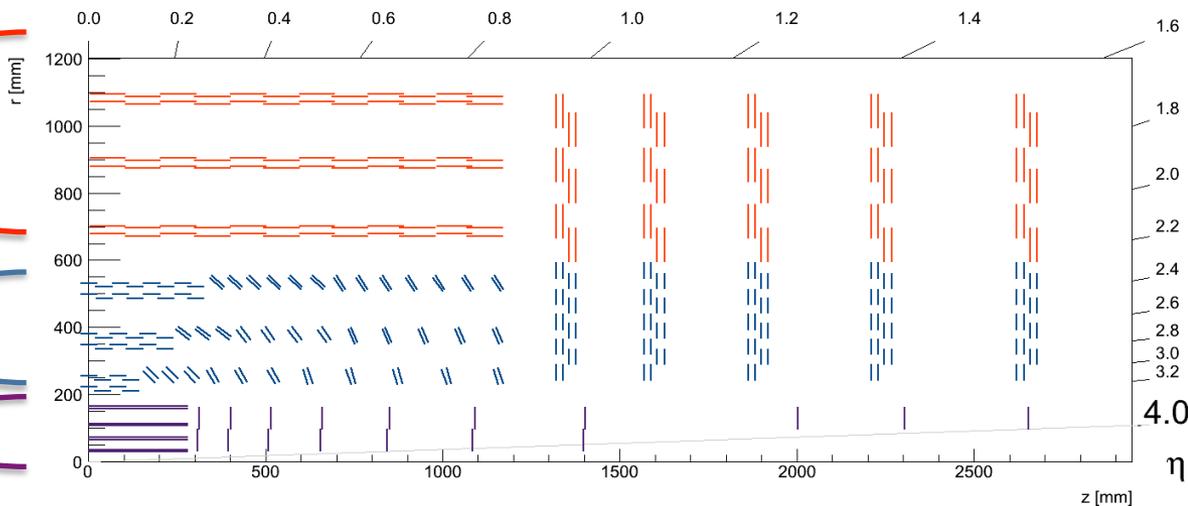
CMS Si Tracker today



Current & Phase1: Planar pixels

- Strip/Strip modules SS**
- Outer Tracker, new Pt modules
- 3 more Pixelated layers
- 5 more Pixelated disks
- 1.5x01.mm² PLANAR pixel size

- Strip/Pixel modules PS**
- Inner Tracker, new
- Disks to η=4
- Pixel modules**



Pixel Area 1.6m² Barrel + 2.0m² Disk
Possible pixel size ~25x100μm² ? Planar plus 1 or 2 layers 3D?

CMS Si Tracker as it could be in 2025

INFN Tracker R&D Phase2

PIXELS

- **New pixel read-out chip 65 nm (ATLAS-CMS)**
 - CHIPX65 (call CSN5 2013)
 - CERN RD53
- **Sensors: 3D (ATLAS-CMS) and active-edge planar**
- Bump-bonding, test beam and irradiations are mandatory
- **Micro-cooling:** evaporating CO₂ finalized to CMS
 - R&D Planar Pixel: cost scale around 0.5 MCHF supported by Germany, Italy, Switzerland, Spain and US
 - R&D 3D Pixel: cost scale of the order of 0.5-1 MCHF supported by Italy, Germany, Spain and USA

TRIGGER

- **Track trigger (ATLAS-CMS)**



Pixel RO-chip R&D:



CHPIX65 (call CSN5 2013) + CERN RD53 (CMS: BA, BG-PV, PD, PG, PI, TO and ATLAS: MI)

- **RD53 first general meeting April 2014 (schedule next slide)**
 - Strong impact of INFN groups (CHPIX65) on several area:
Radiation hardness, Analog-Front end, Digital architecture studies, IP-blocks
- **Milano joined RD53 (already in CHPIX65)**
- **Delay in CERN / TSMC 65nm contract : impact on all RD53 submissions**
 - INFN submission (pixel matrix + IP-block) moved to Fall 2014 [Area: $\sim(3 \times 4) \text{mm}^2$]
- **Memorandum of Understanding almost ready** (signature for June-July)
- **INFN / CHPIX65 will submit designs on silicon to the foundry via MPW:**
 - Small pixel matrix for studies of Very Front End analog designs
 - Synchronous and Asynchronous comparator;
 - Synchronous and Asynchronous FE
 - IP-block prototypes

Pixel matrix PUC dimension 50 μm x 50 μm as agreed in RD53, few details to be discussed.

CHPIX65: Total 10-15 FTE

RD53: 100 members (50% designers)

RD53 Global Schedule as today

- **2014:**
 - **Release of CERN 65nm design kit: Very soon !**
 - Detailed understanding of radiation effects in 65nm
 - Radiation test of few alternative technologies (backup solution).
 - IP block responsibilities defined and appearance of first FE and IP designs/prototypes
 - Simulation framework with realistic hit generation and auto-verification.
 - Alternative architectures defined and efforts to simulate and compare these defined
 - **Common MPW submission 1: First versions of IP blocks and analog FEs**
- **2015:**
 - Common MPW submission 2: Near final versions of IP blocks and FEs.
 - Final versions of IP blocks and FEs: Tested prototypes, documentation, simulation, etc
 - IO interface of pixel chip defined in detail
 - **Global architecture defined and extensively simulated**
 - Common MPW submission 3: Final IPs and Fes, Small pixel array(s)
- **2016:**
 - **Common engineering run: Full sized pixel array chip**
 - Pixel chip tests, radiation tests, beam tests
- **2017:**
 - **Separate or common ATLAS – CMS final pixel chip submissions.**

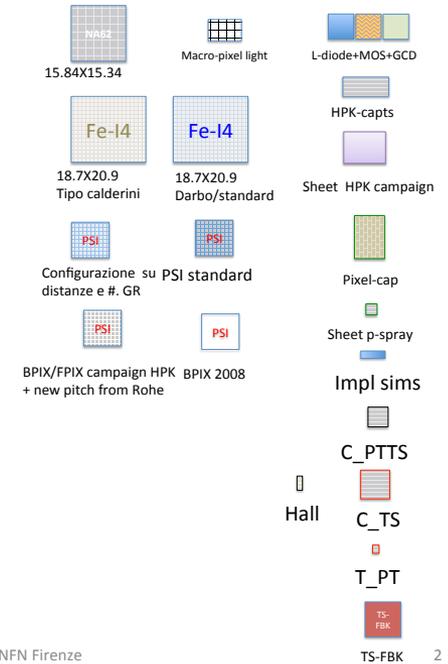
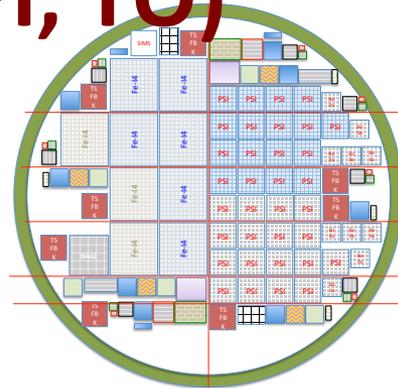
Pixel sensors R&D

Draft Layout discusso il 7/5/2014 alla FBK;
deve essere finalizzato nella seconda meta' di
giugno 2014
Produzione prevista da meta' luglio 2014

(CMS: BA, FI, MIB, PG, PI, TO)

TOTAL CMS FTE 10-15

- **Joint R&D ATLAS_CMS**
➔ **strongly supported by CERN**



09/05/14

M. Meschini, INFN Firenze

- **CMS PLAN:**

- Design of 3D (with ATLAS) and planar pixel sensors: join development with FBK. Also comon CMS batches
- Irradiation: 3 steps up to a 2×10^{16} Neq
- Test Beam
- Micro Channel Cooling: system with evaporative CO_2 to be verified in CMS

Testbeam at FNAL: FBK 3D – May 2014

7 detectors 1E from ATLAS11 FBK production + psi46dig

Characterization and calibration in Torino lab. DAC registers exported to FNAL testbeam.

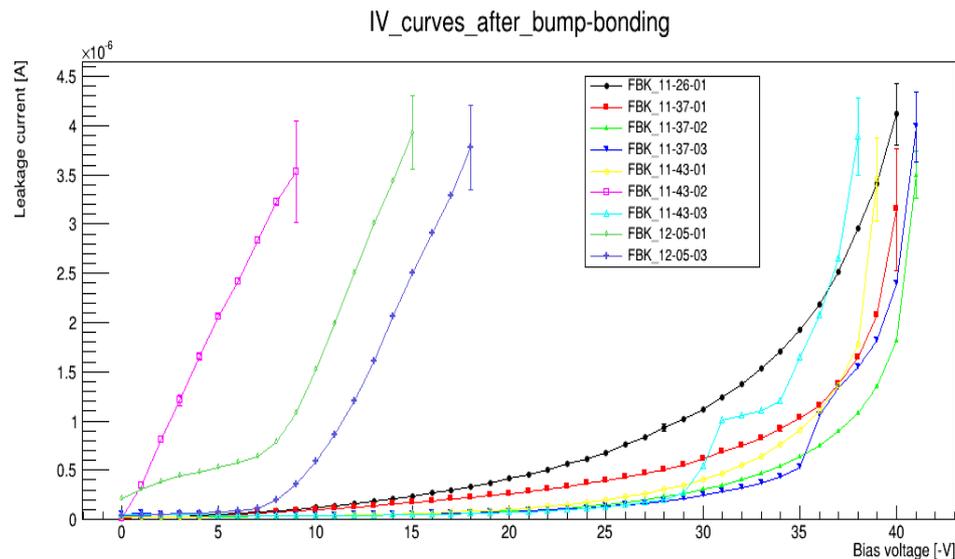
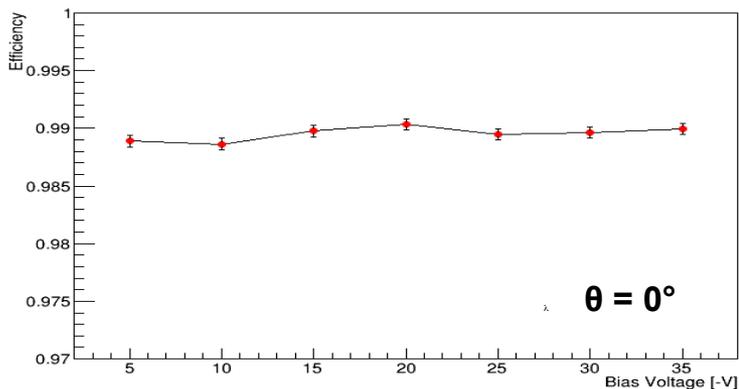
Testbeam analysis ongoing

Preliminary Results:

Threshold ~ 2700 e-

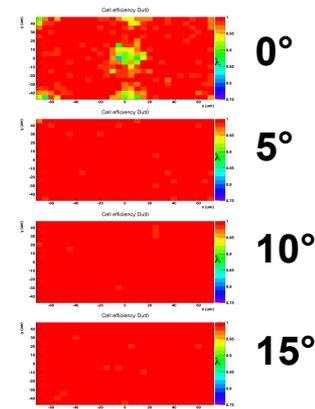
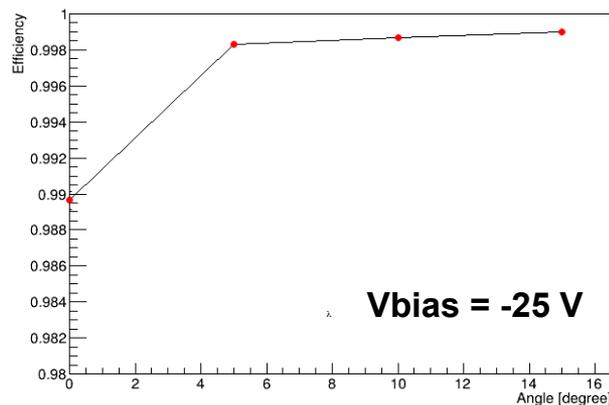
Full efficiency at 0° angle ($>98,5\%$) already at 5 V

FBK_11-43-01: Efficiency vs Bias



Angle scan: Electrode geometrical inefficiency already recovered at 5° (efficiency $> 99,5\%$)

FBK_11-43-01: Efficiency vs Angle



Milestones & Deliverables

- Milestones defined for each R&D item
- Deliverables set according to milestones
- Milestone/Deliverables in common ATLAS/CMS for
 - Sensor production
 - QA/Irradiation/Beam Test of items in sharing

Sensor Production

Date	Milestones
(a)Year1-Q2	1 st planar batch Layout release (ATLAS+CMS)
(b)Year1-Q4	1 st 3D batch Layout release (ATLAS+CMS)
(c)Year2-Q1	2 nd planar batch Layout release
(d)Year2-Q4	2 nd 3D batch Layout release (ATLAS+CMS)
(e)Year3-Q2	3 rd planar batch Layout release

QA Irradiation and Beam Test

Date	Milestones
(f)Year1-Q4	DA & Software Ready for Beam
(g)Year2-Q4	1 st Batch of Planar Pixels Irradiated & Tested on Beam
(h)Year3-Q2	1 st Batch of 3D Pixels Irradiated & Tested on Beam
(i)Year3-Q4	2 nd Batch of Planar Pixels Irradiated & Tested on Beam
(l)Year4-Q2	2 nd Batch of 3D Pixels + 3 rd Planar Pixel Irradiated & Tested on Beam

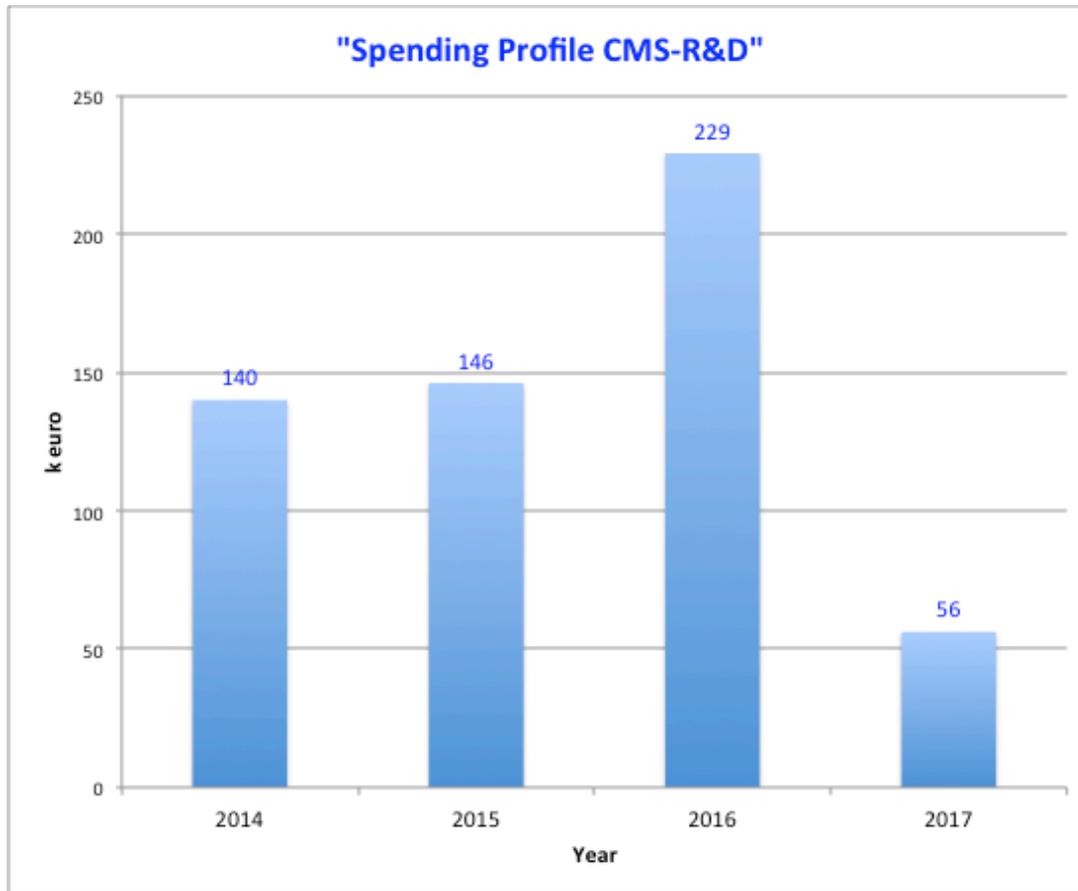
Micro-channel cooling

Date	Milestones
(l)Year1-Q3	Cooling technology plan and simulation results
(m)Year2-Q2	CO2 phase transition in micro-channel
(n)Year3-Q1	Implementation of CO2 cooling in CFRP
(o)Year3-Q4	Optimization of CFRP micro-channel tubes
(p)Year4-Q2	Optimized prototype design

FROM Kick-off														
Year1				Year2					Year3				Year4	
Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	Q3	Q4	Q1	Q2	
M-(a)			M-(b)	M-(c)			M-(d)		M-(e)					
			M-(f)				M-(g)		M-(h)		M-(i)		M-(l)	
		M-(m)			M-(n)			M-(o)			M-(p)		M-(q)	

Sensors
QA/Irr/TB
Cooling

Spending Profile 2014-2017



CMS-R&D 572k€

Cost Summary	572
Sensors	194
Bump Bond	203
Test & Assembly	50
Irrad & Test Beam	65
Micro cooling	60

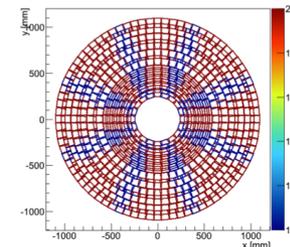
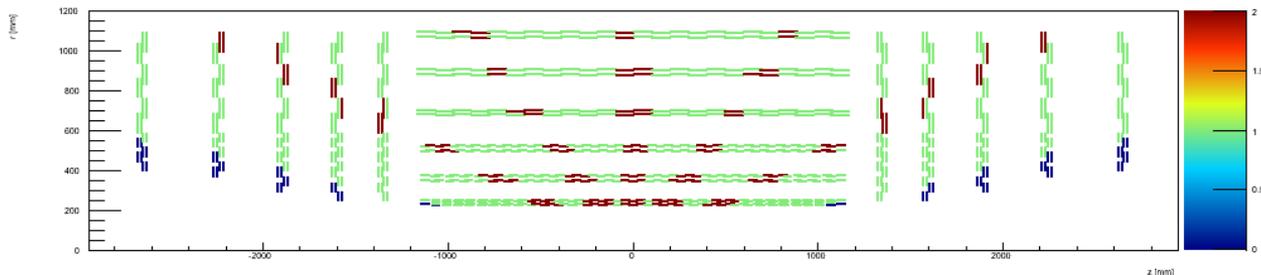
Costs of “common” activities with ATLAS 204k€



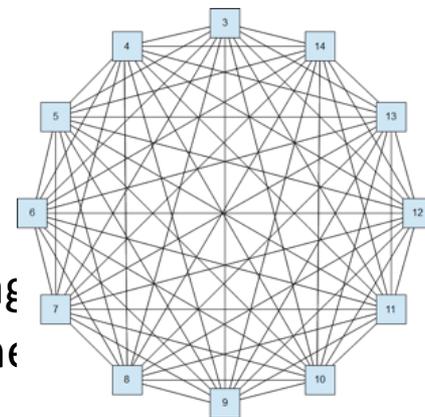
CMS L1 Track Trigger approach



- Subdivide tracker into trigger towers
- $8(r-\varphi) \times 6(r-z)$ trigger sectors (some 10% overlapping)
 - Each sector ~ 200 stubs on average; tails up to ~ 500 stubs/event in 140 evts pileup+ttbar
 - About 600 Gb/s per one trigger tower



- Send data to Track-finding processors
- Full mesh ATCA shelves
 - “40G” full-mesh backplane on 14 slots = 7.2 Tb/s
 - time multiplexing data transfer from a set of receiving boards to pattern recognition and track finding engine
 - $O(10)$ time multiplexed at the shelf level





Track Trigger: FLAM 2014-2018 (FI, LNF, MI, PD, PG, PI, SI, TS)

- feasibility studies of a L1 track-trigger with existing technologies, especially in the field of high bandwidth communication, both ATLAS and CMS
- development of beyond the state-of-the-art technologies for Associative Memory chips, both ATLAS and CMS

The proposed R&D is a significant advancement over the state of the art of the FTK processor with innovative content, especially in the design of a full-ATCA based processor and the realization of a System-in-Package that is a first (or early) use case at INFN and in the HEP community.

- Four Work Packages have been identified to deploy the R&D:
 - WP1: Simulation and Physics studies
 - WP2: High bandwidth communication
 - WP3: New generation Associative Memory chip
 - WP4: Packaging technologies

Total FTE 13.3 (ATLAS 4.0, CMS 9.3)



FLAM Work-packges and costs



1. L1 simulation studies
2. Development of a “system demonstrator” based on full-mesh ATCA and AM chip technology
 - Develop a viable solution to L1 Track trigger architecture, and support the ATLAS and CMS Trackers design choice

Timeline for CMS and ATLAS TDRs ~2017
3. New generation AM chip
 - Increase pattern bank density, speed and lower the power consumption
 - Use “best foreseeable technology” for HL-LHC
4. System on Chip – Packaging AM + FPGA
 - Reduce trigger latency by including in the same package the new AM chip and FPGA – ideally 1:1

PROJECT TIMELINE AND COSTS

WP	No.	Activity	Date	Cost (k€)
1	1.1	System simulation in Verilog/SystemC	2014-17	
	1.2	Development of physics algorithms and study impacts on the system	2014-17	
2	2.1	Development of a FMC mezzanine	2014	20
	2.2	ATCA test-stands	2015	16
			2016	16
	2.3	Pulsars and AMchips per test-stands	2015	26
			2016	26
	2.4	First demo stand running	2015	
2.5	Final test with AM06	2016		
2.6	Test with AMSIP	2018		
3	3.1	Miniasic design	2015	46
	3.2	Miniasic submission and test	2016	
	3.3	Design and submission of MPW for AMSIP	2016	90
			2017	
4	4.1	Naked FPGA	2017	50
	4.2	Submission of multipackaging (AMSIP)	2017	150
	4.3	Mezzanine with AMSIP	2018	10
Total cost (k€)				450

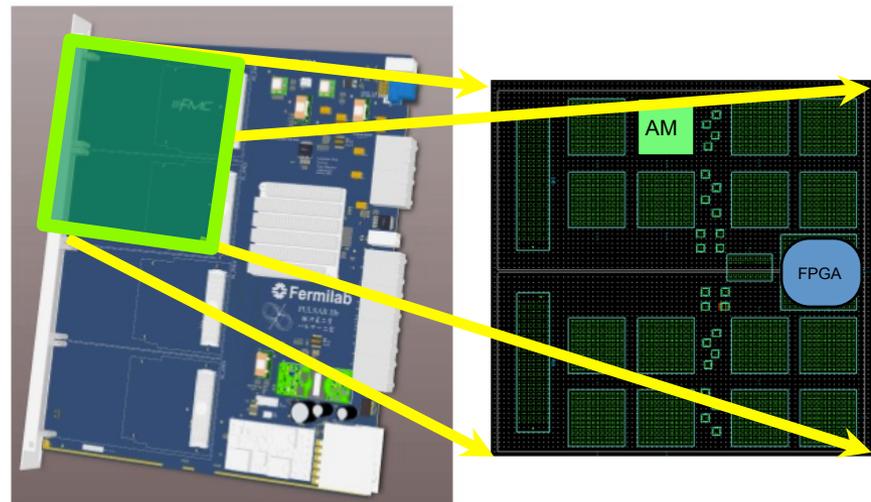


AM INFN Mezzanine (the heart)

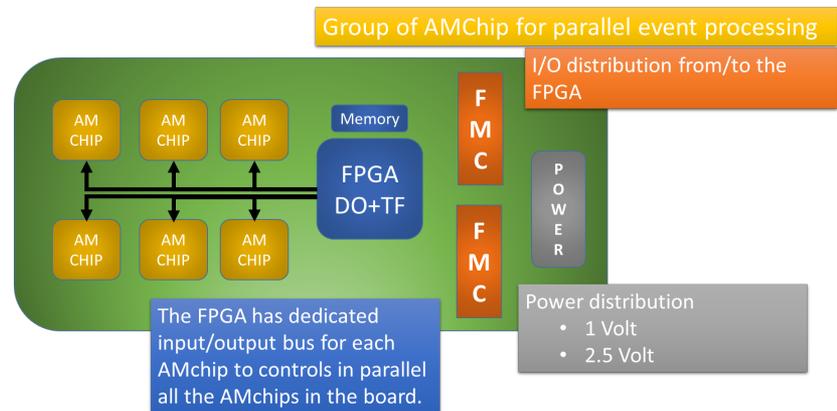


A double FMC mezzanine to be mounted on Pulsar IIb (FNAL)

- Could work with (up to)
 - 16 AM05 chips (48 Kpatterns)
 - 10 AM06 chips (1.28 Mpatterns) due to power limitations
- FPGA: Kintex7
 - 1440 DSP (for PCA fit)
 - 3 MB internal memory
- Additional memory (72 MB)



Design of PCB finalized
ready to order in 2014 → 20 keu





Future progress: WP 3-4

FTK could become smaller and smaller

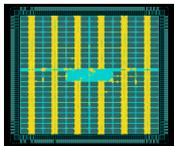
Multi-packaging FPGA & AMchip – **mini FTK**

WP4 (FPGA+AM chip) adatto per un FIRB



R&D coordinated with Fermilab

AMchip06 FTK
Design ends in 2014



Full custom AM cell
R&D limited by FTK schedule



Miniasic 40nm
~3mm²
Cheap AM cell
R&D
2015-16



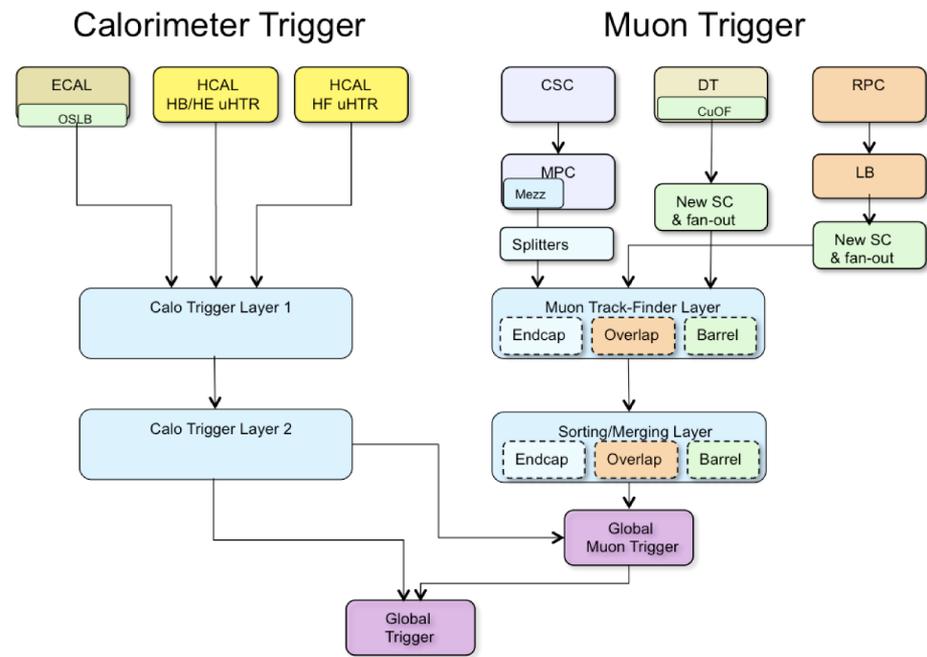
MPW 40nm
~12mm²
usable for ATCA
demonstrator
& system in
package
2016-17

**1 AM chip
1 FPGA in the
same package**

New Amchip: 28 or 40 nm (200+ MHz?, new functionalities for L1)
Considering also 28 nm technology with similar budget for MPW
(half minimum area)

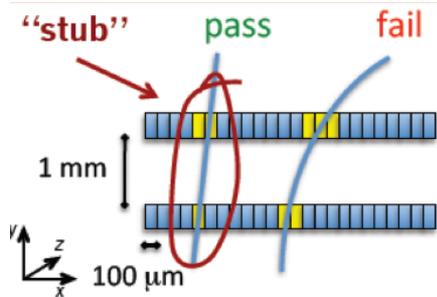
Trigger Phase 1 & 2

From year 2016, all the muon data will be used in a unique algorithm in order to have more robust system in the view of the lumi/background increment planned.

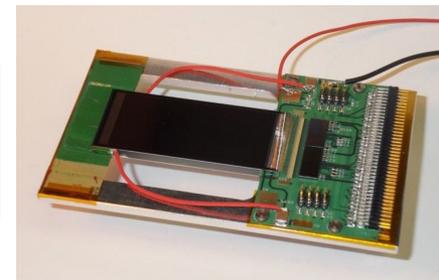


Increase L1 Trigger rate from 100 kHz to 500 kHz ... 1 MHz
Increase L1 Trigger latency from 4 μ s to 10 μ s

the upgraded silicon strip tracker is being designed with triggering capabilities: layers are composed by pair of modules ...

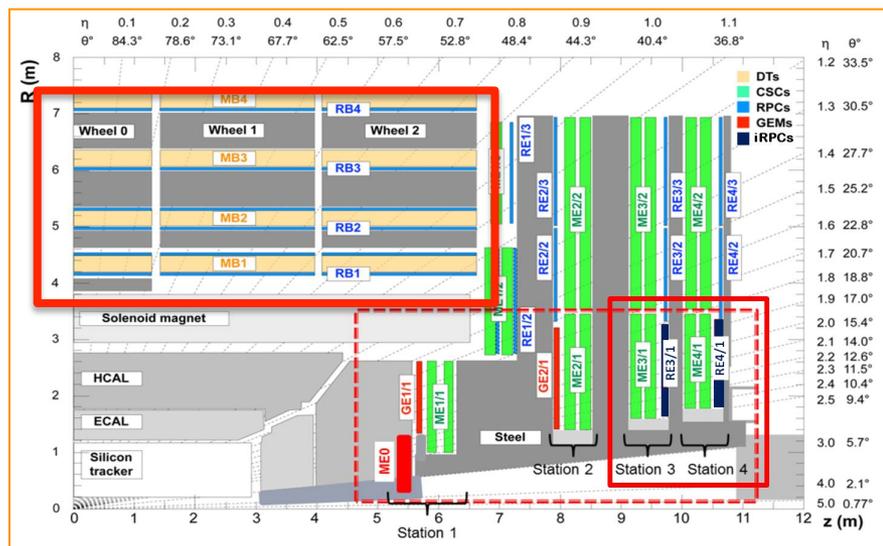


2 prototypes tested at DESY - 2 CBC chips - FPGA emulation of concentrator and of GBT on GLIB prototype DAQ board – **validated trigger concept**



All Outer Tracker modules are trigger modules

Phase 2 Muon system



At present:

Barrel muon system covered with:
8 layers of chambers (58 hits max)

Endcap region covered with:

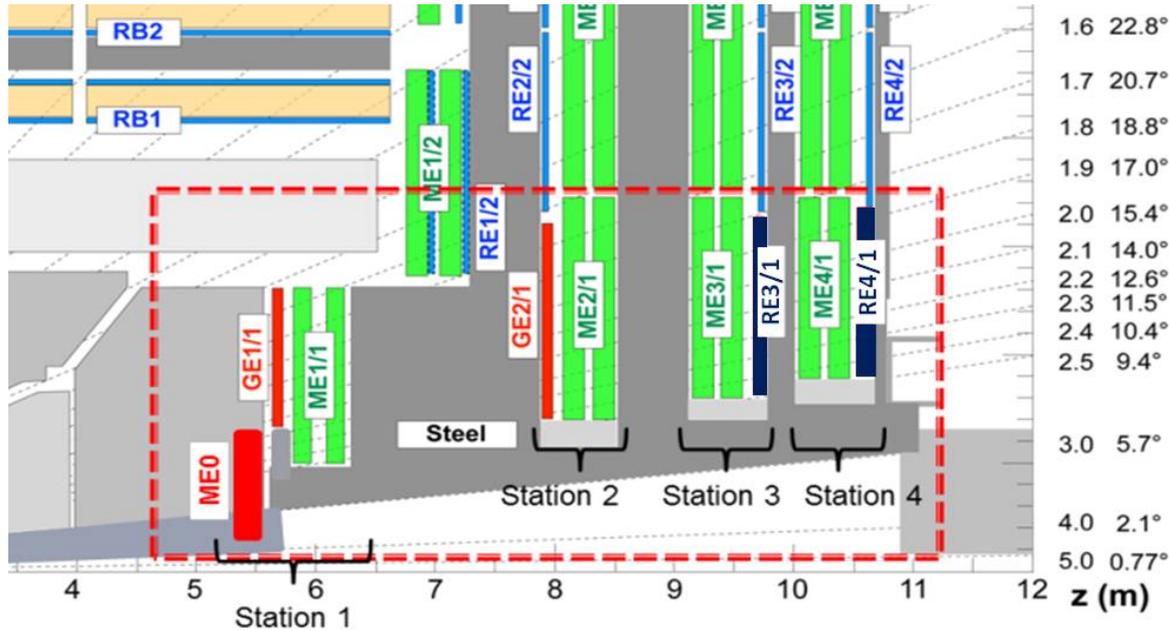
8 layers (28 hits max)

High eta region covered with:

4 layers (24 hits max)

- **Existing detectors worked very well:** large investment to be protected
 - All types of chambers (RPC, CSC, DT, GEM) to be tested for aging at
5x higher rates/6x higher doses in the GIF++ facility starting early 2015
 must continue to operate without significant degradation → **consolidation**
- **Barrel DT minicrates replacement:** obsolescence of ASICs and new L1 trigger, improved trigger performance
- **Muon enhancements in forward $1.6 < |\eta| < 2.4$ region**
for redundancy and trigger: addition of small GEM and RPC in all four stations
- **Extension to the far forward region $|\eta| > 2.4$:** a single muon tagging station
- **Need to reduce global warming footprint:** RPC eco-friendly gas studies

RPC (BA, LNF, NA, PV)



RE3/1 & RE4/1
proposed to cover
very forward region

$$1.6 < |\eta| < 2.4$$

144 chambers ($\sim 1.5\text{-}2.0 \text{ m}^2$ area) for inner ring 1 of disks 3 and 4

Rate: $1\text{-}2 \text{ kHz/cm}^2 \rightarrow$ **x5 limit tested for existing RPC**

Integrated charge: $1\text{-}2 \text{ C/cm}^2 @ 3000 \text{ fb}^{-1}$

Background rejection and muon reconstruction at HL-LHC

keep trigger performance and low ($p_T < 20 \text{ GeV}$) threshold
without significant performance degradation

Constant trigger rate with $p_T < 20 \text{ GeV}$

Joint ATLAS-CMS phase 2 R&D: 2014-17

Operation: 1-2 kHz/cm² ; 1-2 C/cm² @3000 fb⁻¹ with improved time resolution (10-100) ps

iRPC

- Large area, improved:

- Thin gap
- Multigap
- High voltage connections
- Gas distribution and inlet

- with HPL / glass electrodes:

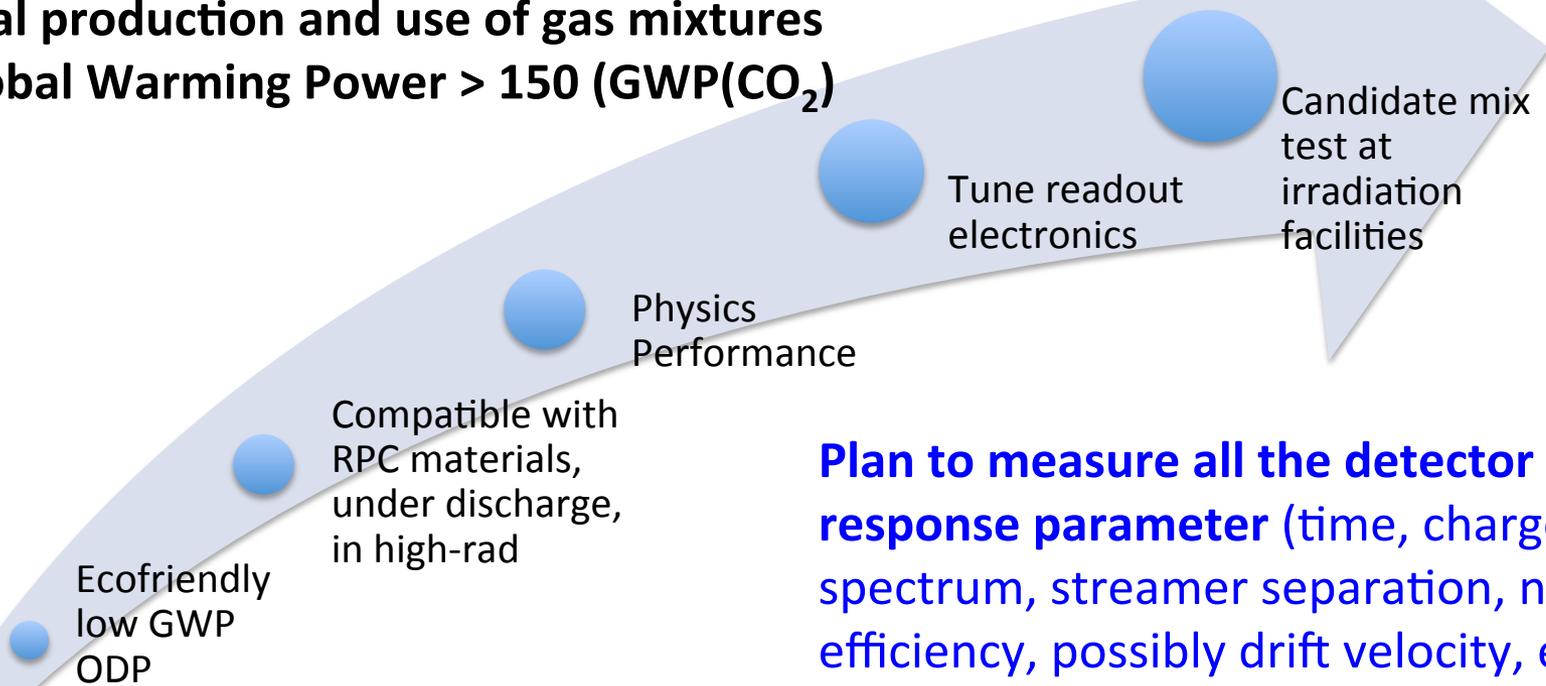
- Lower resistivity materials
- Thinner electrodes to be tested to improve the S/N ratio, the spatial resolution and to reduce the stress (HV working point) and the aging

Total CMS FTE 5

- construction of a small set of **reduced size prototypes** (thin, multi-gap, different resistivity...) for a maximum of 10 chambers to test in common (ATLAS/CMS)
- construction of **prototypes** that fit all the specific requirements of both experiments
- **Aging test on detectors and materials at GIF++** (strong gamma-ray source, muon-beam, cosmics)
- **Beam test facility at Frascati:** rate, efficiency, time resolution, sensitivity to photons and neutron
- **Test of FE electronics (aging and SEE) at various facilities** (GIF++, Louvain, ...)
verify currently installed boards for 10-year equivalent dose at HL-LHC

The Quest for ecogases: Search Process

The European Community has limited the industrial production and use of gas mixtures with Global Warming Power > 150 (GWP(CO₂))



Plan to measure all the detector response parameter (time, charge spectrum, streamer separation, noise, efficiency, possibly drift velocity, etc)

C₂H₂F₄ is the main component of the present RPC gas mixture:

GWP(C₂H₂F₄) = 1430, GWP(SF₆) = 23900, GWP(iC₂H₁₀) = 3.3

C₂H₂F₄ and SF₆ are crucial to ensure a stable working point in avalanche mode

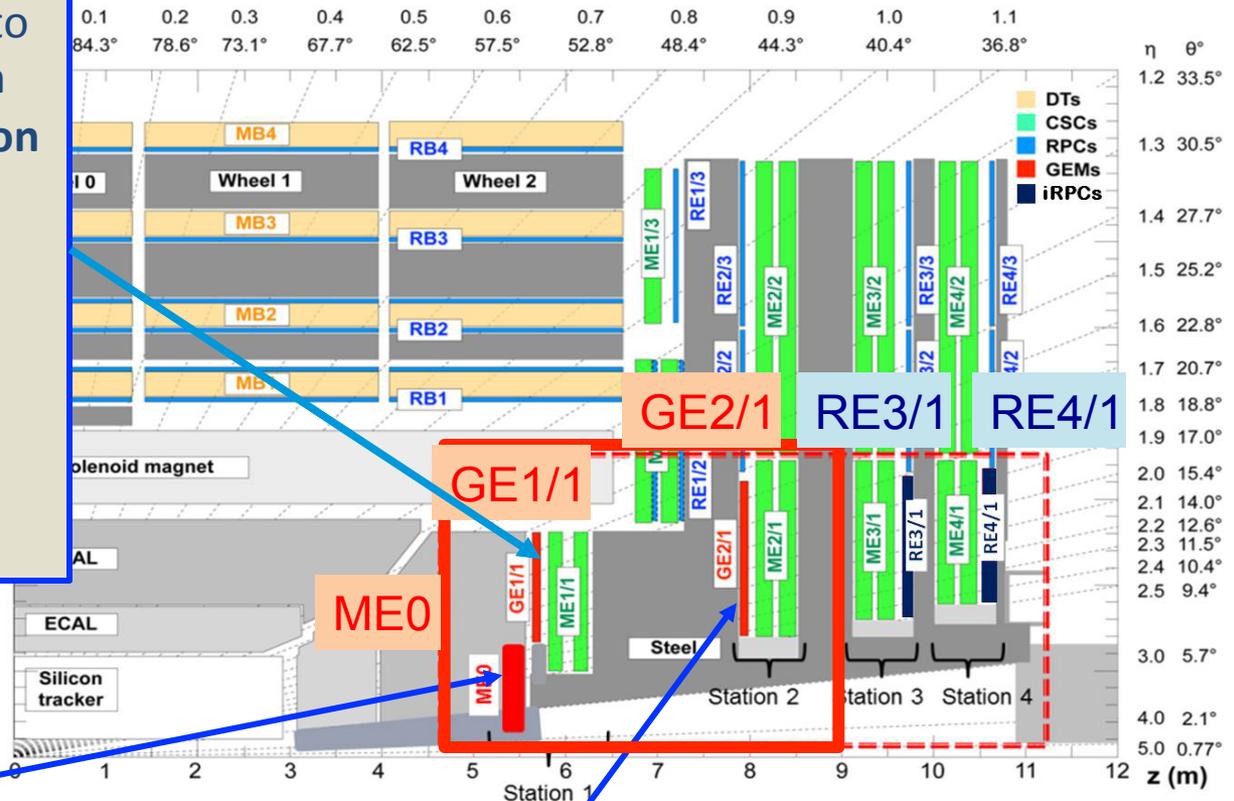
Similar problem for CF₄ (GWP = 5800) used in GEMs for time resolution

GEM Upgrade project (BA, BO, LNF, NA, PV)

Total: 10-19 FTE (2014-2017)

Phase1 LS2

- ▶ **GE1/1**: precision chambers to improve trigger momentum selectivity and reconstruction during late Phase1 and throughout Phase2
- ▶ Demonstrator in YETS2016 approved
- ▶ TDR by October 2014



Phase2 LS3

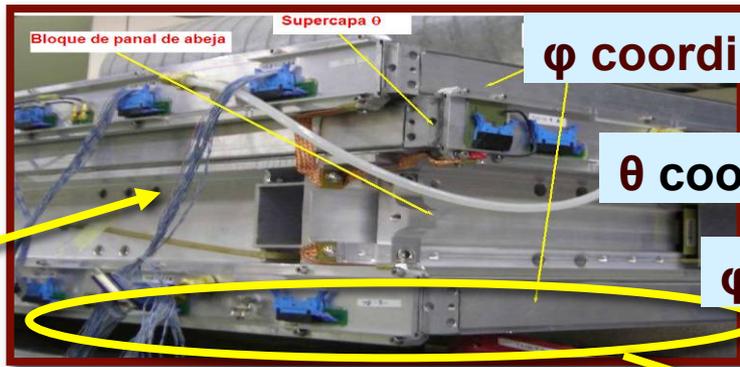
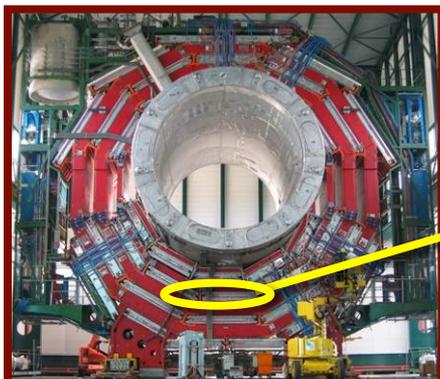
- ▶ **ME0** module to provide muon tag in highest eta region ($\eta=4$)
- ▶ Several tens of kHz expected \rightarrow GEM
- ▶ R&D for ME0 launched

Phase2 LS3

- ▶ **GE2/1**: 20 degrees precision chamber up to $\eta=2.45$ to improve trigger momentum selectivity and reconstruction

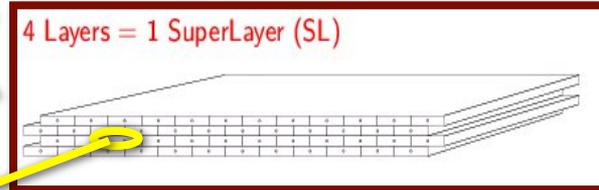
In preparation: CALL CSN5 GEM (INTERDISCIPLINARY)

250 DT chambers + minicrates (50% INFN, 25% CIEMAT, 25% Aachen)



Superlayer

ϕ coordinate

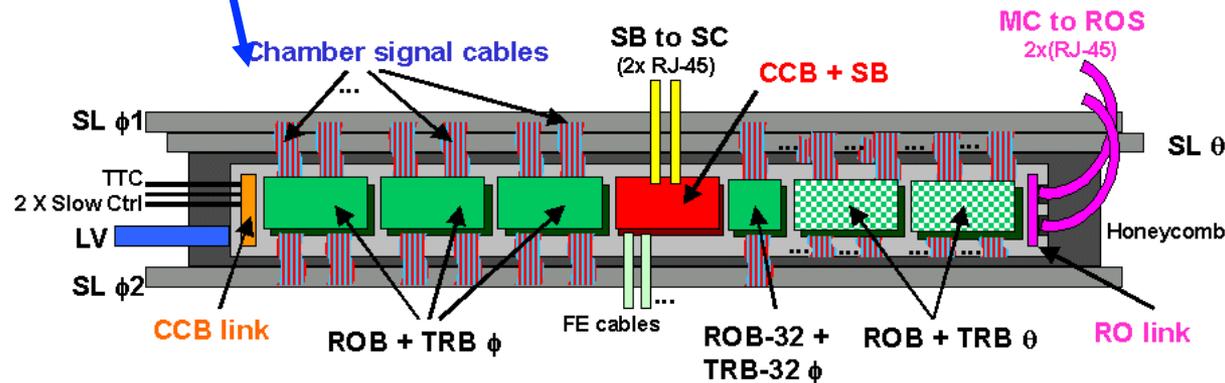


Cell

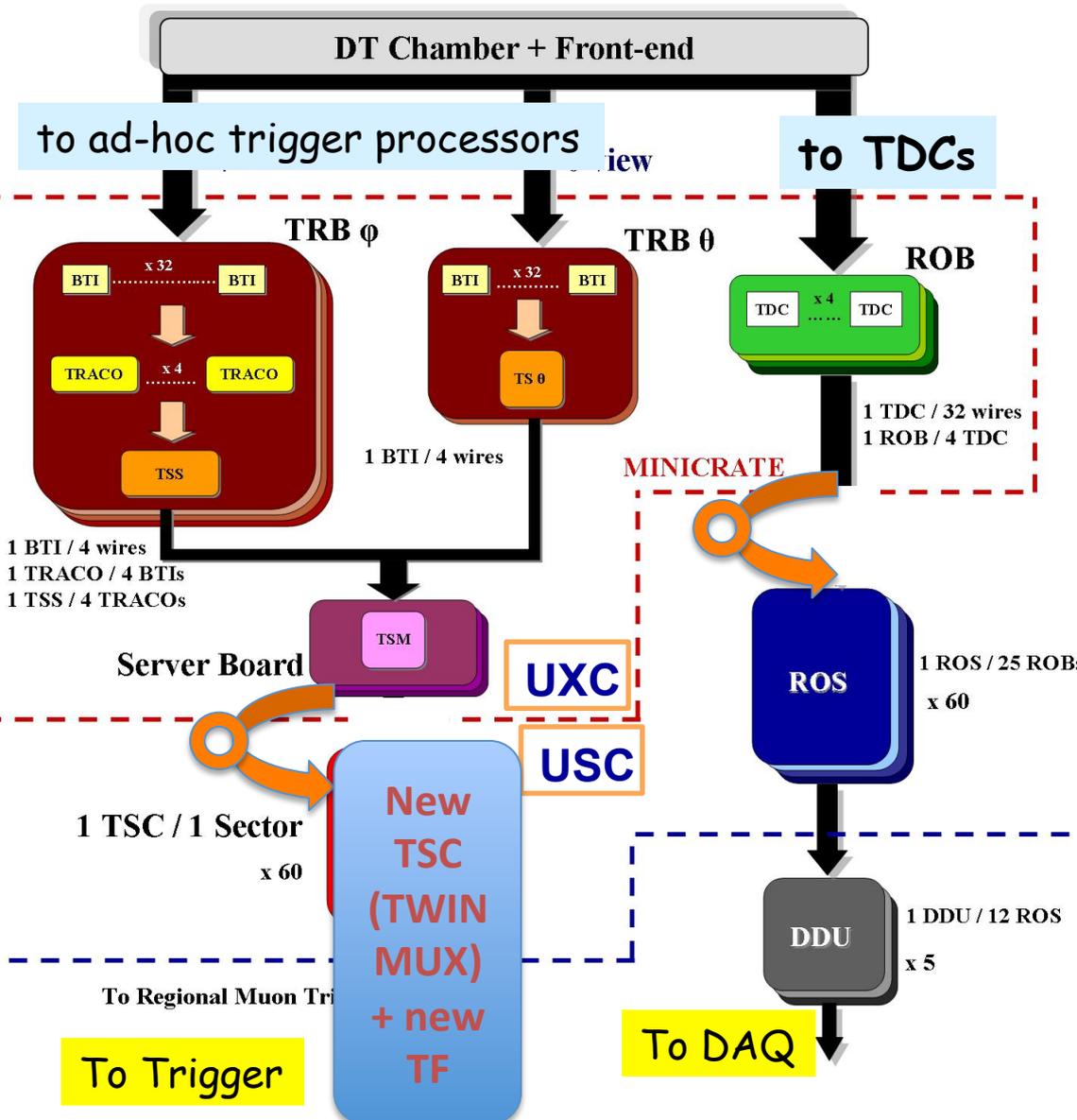


a wonderful and unique detector:

Although based on drift tubes (drift time of 400 ns), it has proven from the very beginning to provide a **robust, efficient, pure trigger** with synchronization and **timing information with uncertainty below 1 ns**



DT electronics for Phase 1



Sector Collector moved to USC

Second level of DT read-out and trigger

TWINMUX could have inputs also from RPC and HO. Improve rejection against low Pt.

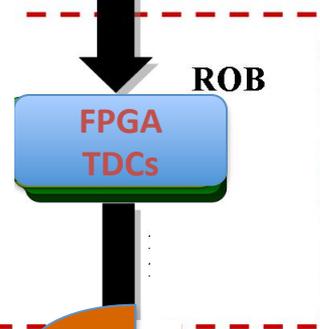
3500 optical links

DT electronics for Phase 2

DT Chamber + Front-end

Total: 4-8 FTE (2014-2017)

Replace the chamber MCs with:
-- a system of TDCs on the chambers;
TDC data continuously transmitted to USC on optical fibers
-- processors in USC that, besides performing high-speed ReadOut operations of the high-resolution TDC data, also generate a muon trigger for CMS directly from the TDC data



UXC

TDCs on chambers



USC

Trigger generated directly by processing TDC data (as the HLT & offline tracking)



To Trigger

To DAQ

DT electronics Phase 2

Project workplan is at a very early stage. However there exist time constraints driven by the LHC schedule:

Installation of the new electronics planned for the Long Shutdown LS3 in 2024

2020/21 until LS3: 4 years construction

- R&D phase
- ✓ 2015/16: study and discuss overall architecture.
 - ✓ Until LS2 in 2019/20: Development of the physical components, testing and system prototyping, with the new-minicrate electronics and new USC electronics being developed in parallel.

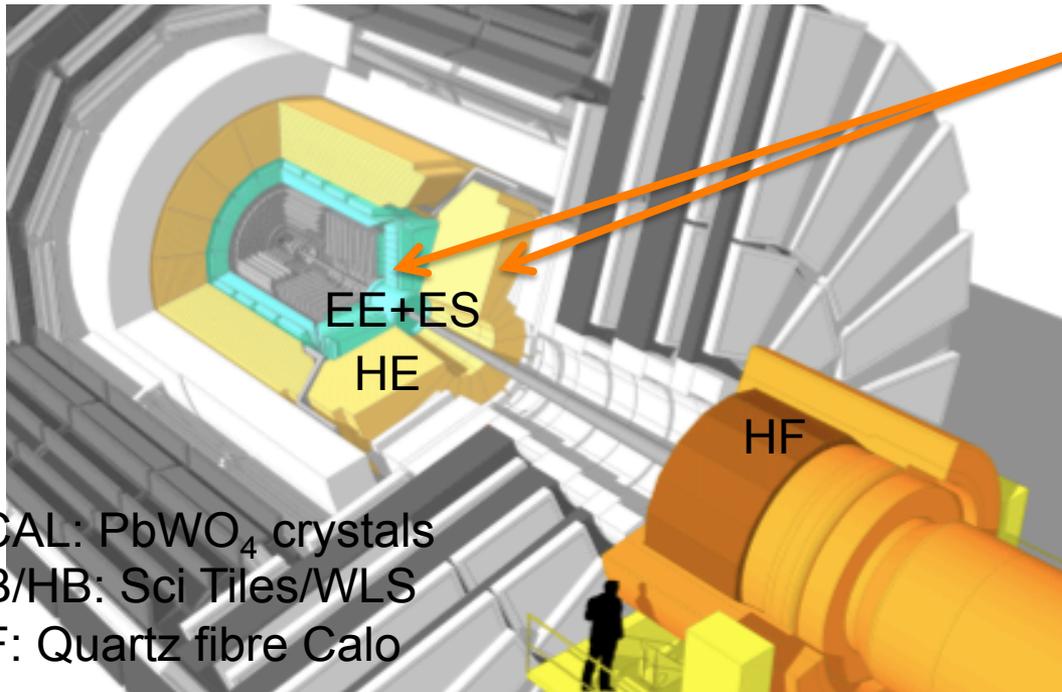
Strategy: design based on commercial hardware of CMS-wide use

Innovative aspects are in the firmware:

- A high-performance TDCs algorithm, developed and implemented in radiation tolerant FPGAs, in collaboration with CIEMAT
- A hit detection and track fitting algorithm for processing the TDC data and generate a trigger primitive, to be developed and implemented in FPGAs.

Endcap calorimeters: longevity appraisal and upgrade plan

- *Substantial* performance degradation in the ECAL and HCAL endcaps
- *Moderate* damage in the ECAL and HCAL barrel
 - Increase of APD dark current in ECAL will require mitigation
- Moderate degradation in HF (operable throughout Phase II)



ECAL: PbWO_4 crystals
HB/HB: Sci Tiles/WLS
HF: Quartz fibre Calo

- Replacement/upgrade of both ECAL and HCAL endcaps in LS3
- Upgrade of the ECAL FE electronics: 40 MHz data stream (barrel)
 - HCAL upgrade in LS2
- *Possible* mitigation of the APD current noise
 - VFE with faster shaping time (also, improved timing, spike rejection)
 - Cooling of the barrel

Endcap calorimeter options

- Down-selection from 3 to 2 at the beginning of April 2014

1) Maintain current structure

- Replace ECAL and refurbish HCAL with rad-hard technologies, improved compactness and granularity
- *“Emphasis on photon reconstruction”*

2) ~~Merge EM and HAD compartments into a (rad-hard) dual readout fibre calorimeter~~

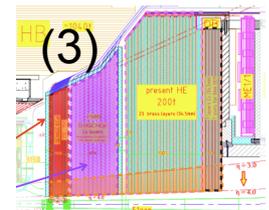
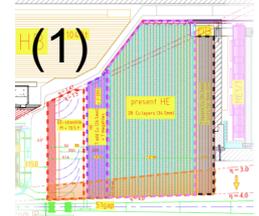
- *“Emphasis on jet resolution”*

3) Finely segmented calorimeter

- (600 m² silicon pads in W/Cu structure)
- *“Readout as much information as possible”*

• R&D on fibres encouraged to continue

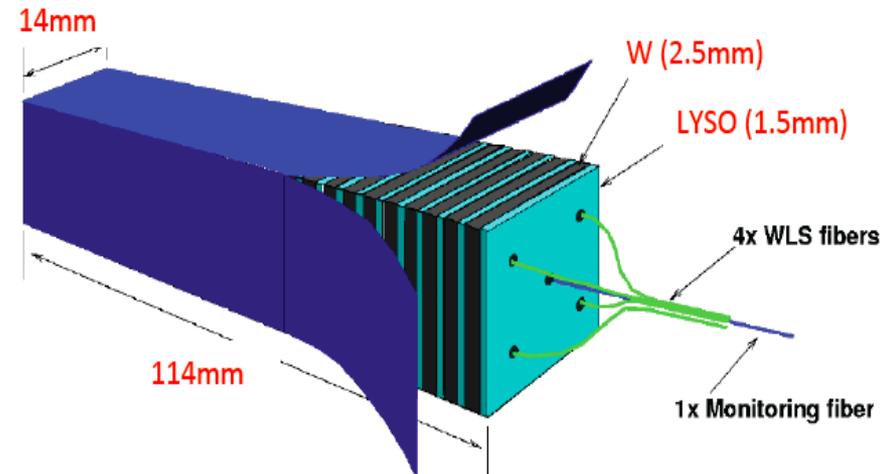
- Vital WLS component for option 1)
- Provide alternative solutions to option 1)



I WILL NOT DISCUSS
OPTION 3) TODAY

EM endcap calorimeter with optical readout

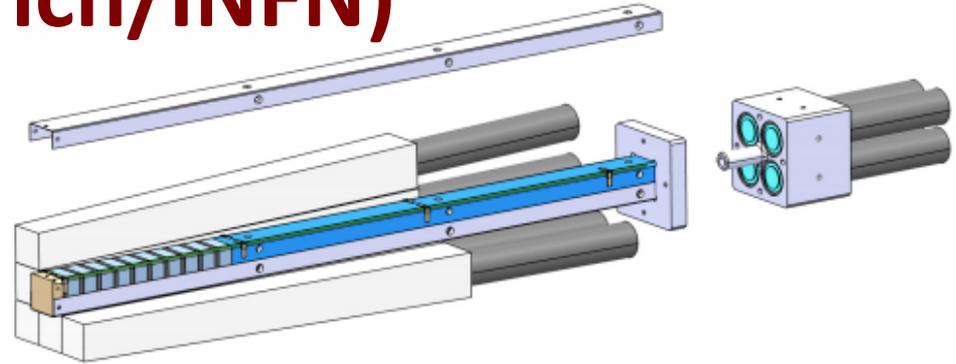
- Main features
 - LYSO / W (or CeF_3 / W)
 - Molière radius 1.4 cm (2.2 cm in PbWO_4)
 - Energy resolution $\sim 12\%/ \sqrt{E}$ (+) 1%
- Major challenges and R&Ds
 - Rad-hard WLS fibre
 - Capillary with WLS liquid
 - $\text{SiO}_2:\text{Ce}$ matches CeF_3 emission spectrum
 - Photosensors:
 - GaInP-PM on detector: very challenging
 - Si-PM at remote location (or cooled??)
 - Rad-hard PMTs
 - Crystal production (and rad-hardness)
- Cost drivers:
 - Crystals and readout



- Resolution comparable to current calorimeter
 - Stochastic term $\sim 15\%/ \sqrt{E}$
- Pileup resilience
 - Compact shower size (small Molière radius) and fine transverse granularity
 - Fast response (and 50 ps timing capability)
- Tower structure to facilitate integration in the CMS reconstruction and trigger

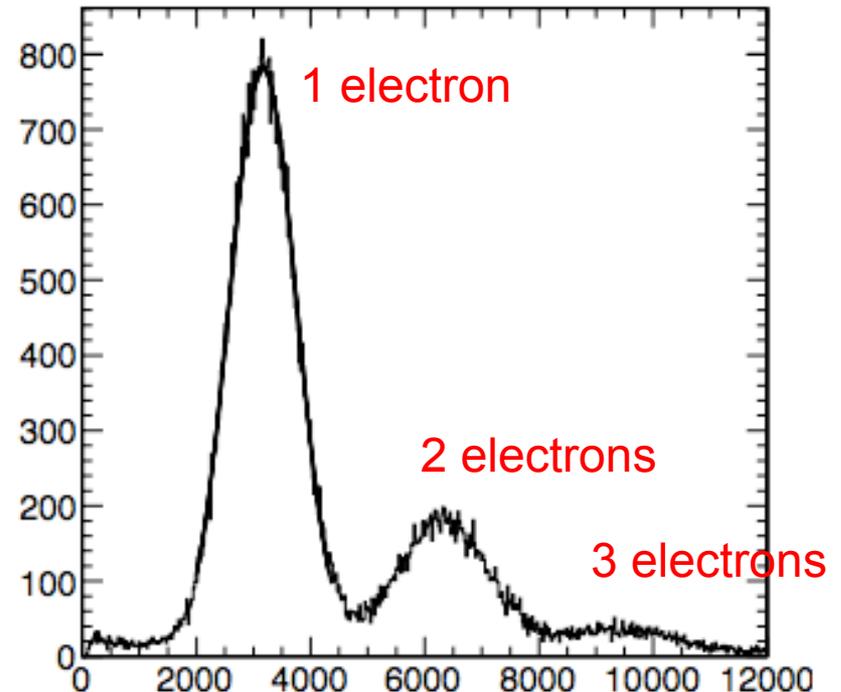
Test beam at LNF-BTF with CeF_3 - shashlik (ETH-Zurich/INFN)

- Central $2.4 \times 2.4 \text{ cm}^2$ tower: 10 layers
 - 10 mm CeF_3 crystals / 3 mm W plates,
 - Kuraray plastic WLS fibres in the corners
 - Aim at testing $\text{SiO}_2:\text{Ce}$
- Shower containment and additional setup
 - Matrix of 8 BGO crystals
 - Beam hodoscope with 1 mm pitch x-y for position scan



- Beam energy 500 MeV
 - Resolution $\sim 12\%$ @ 1 GeV
 - N p.e. $\sim 200-300$ / GeV

- ▶ Next at high energy beam (SPS) November 2014
 - ▶ Possibly with $\text{SiO}_2:\text{Ce}$ as WLS



Alternative R&D opportunity: fibre calorimeter (spacal)

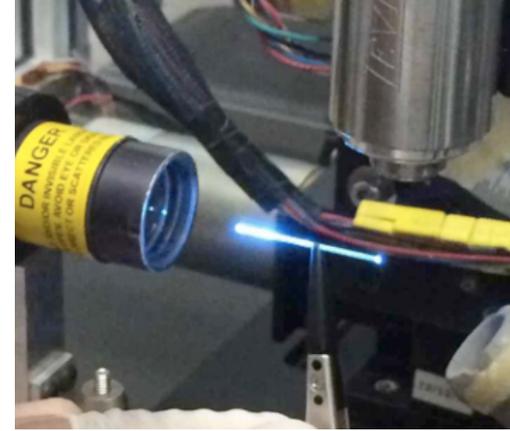
Parameterization:
 σ_E/E (samp) $\sim 2.7\% \sqrt{(d/f_{\text{samp}})}$

Absorber	ρ (g/cm ³)	f_{samp}	$\sigma_{E_{\text{samp}}/E}$ (%)	X_0 (cm)	R_M (cm)
Cu	7.64	0.068	9.26	1.87	2.0
Pb	9.56	0.054	10.35	0.71	2.2
W:Cu (70:30)	13.48	0.039	12.30	0.55	1.7
W	15.96	0.033	13.38	0.45	1.6

Table 1. Expectations for a quartz-fibre calorimeter; the sampling fraction f_{samp} is given by the fibre to total mass ratio.

- Compactness and sampling term comparable to crystal shashlik
 - Transverse granularity virtually very high (defined by the readout pitch)
- R&D challenges
 - Photodetectors (common to Shashlik)
 - Radhad fibre with sufficient light output (at least 100 p.e./GeV for 10%/VE)
- Fibres as active medium provide *flexibility in the design* and potentially *lower costs* than calorimeters based on crystal or silicon as active media.

R&D Plan for 2014-2016 (MIB, RM1, TO, TS)



- BTF test beam on iMCP (CSN5 project MIB-RM1) now
- Replacement of the plastic fibres with SiO₂:Ce fibres for WLS in the CeF3 shashlik
- Production of a **single W/Cu tower 2.4x2.4 cm²** to be tested in the BGO matrix
 - Need 1000 fibres with 0.8 mm diameter + mechanics
- Production of a full 3x3 prototype in W/Cu configurable (could host different type of fibres) to be tested in 2015
- Summary: 30 keu for prototyping in **2014**
- **2015-2016:**
 - ✓ Rad hard fibers R&D
 - ✓ Rad hard SiPM with FBK
 - ✓ Mechanical structure

Total: 4-6 FTE (2014-2016)

CMS phase 2 R&D - summary

R&D CMS FASE2			sett 2013	2014	TOTALE	ATL+CMS	ANNI	FTE	commento
TRACKER	PIXEL	sensori		64	194	1123	2014-2017	9-14	include assegnazione CMS 0.5*65keu feb14 (ATLAS GE)
		BB		27	185				
test			20	50					
irraggiamenti microcooling			20	65 60					
	TRIGGER	track trigger		20	233	450	2014-2017	9.3	
MUONI	RPC	elettrodi			27	277	2015-2017	5	
		prototipi			37				
	FE			32					
		ecogas		5	18				
		GIF,BTF, etc			24				
	DT	irraggiamenti elettronica			11 250	261	2015-2019	4-8	
	GEM	irraggiamenti prototipi		15			2015-2017	3.5	nuova attivita' PV GE1/1 call interdisciplinare CSN5
CALO	BARREL	irraggiamenti elettronica FE	12				2013-2014 2016-2017		invecchiamento APD fase prototipi - studi in corso
	ENDCAP	fibre fotorivelatori meccanica timing	15 15	20 10	200-250	300	2014-2016	4.5	in fase di finalizzazione progetto finanziato CSN5 2014-15
TOTALE			42	201	1186	2411			

External Funds and Resources

- **PRIN: H-TEAM:** MIUR 2014-2016 (321 keu) CMS+ATLAS 7 assegni biennali (uno per sede)
Univ PI (atlas-cms), Univ TO (cms), Univ SI-FI (cms), INFN PG (CMS) - MI (atlas)
- **AIDA-1 program 2012-2015:** BA, BO, FE, GE, LNF, LE, MI, PD, PV, PG.PI, RM2
 - ✓ irradiations of the CMS-HPK campaign
 - ✓
 - ✓ ...
- **FP7-PEOPLE-ITN INFIERI:** art 23 da settembre 2014
- **AIDA-2 under construction:**
 - ✓ 3D sensors and Pixel modules for HL-LHC upgrade of ATLAS and CMS
 - ✓ Microelettronica
 - ✓ iRPC on WG12 Gas detectors
 - 12.1.1 Ecogas (**Tor Vergata, Bari, LNF, ...**)
 - 12.1.2 Electrodes (**Coimbra, Bari, LNF,...**)
 - 12.1.5 High rate and fine resolution RPC (**Tor Vergata, Bari, ...**)
 - 12.3.6 Standard production protocols of optimized RPC components for technology dissemination (**Bari, LNF, Coimbra, MPI,...**)
 - ✓ Optical read-out calorimeters on WG15: test benches for fibers characterization, photodetectors, irradiation, test beam and mechanical prototypes

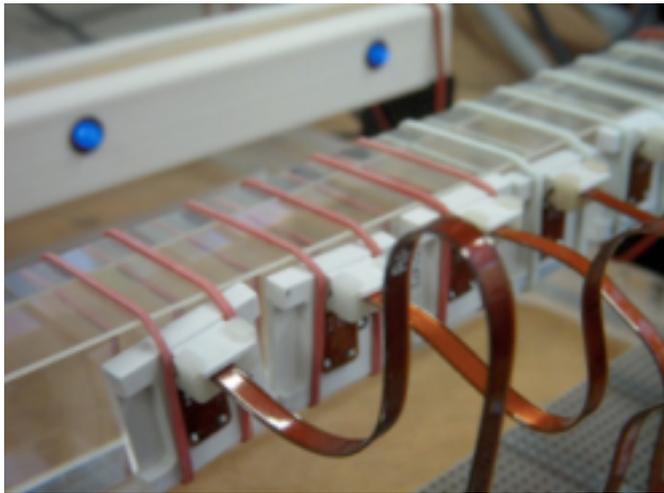
BONUS



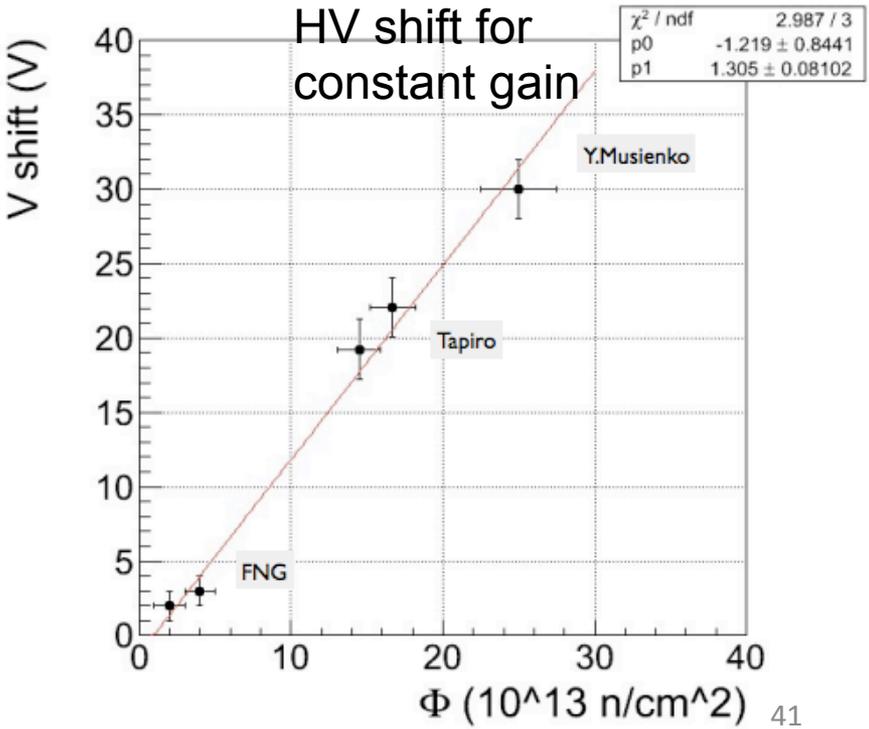
DT phase2 electronics workplan generalities

- Although the architecture to be studied in 2015/16, an effort is going in CMS for estimating the total cost of the new DT electronics, based on today's HW with reasonable extrapolation factors. A first iteration cost table is being scrutinized.
- the R&D is based on today's HW. For the trigger R&D of INFN interest, a cost of 250 Keuro can be estimated from the cost of the basic items:
 - Microsemi and Xilinx FPGAs, optical links (GBT components, Versatile links), PCBs fabrication and components assembly (3 different boards will have to be produced, with 2 submissions each), aluminum extrusions, uTCA crates with PS and interface boards, high-end CMS uTCA cards, testing equipment (pattern units).
 - This is ~50% of the total R&D cost, and represents ~4% of the estimated total cost of the Drift-tubes Electronics upgrade for LHC Phase-2.
 - expenditure will start not earlier than 2016, after the study phase, and will cover until LS2 in 2019/20.

Further appraisal of APD longevity ongoing



- Irradiation at neutron fluence 10^{13} - 5×10^{14} cm^{-2}
 - 4 APDs at Frascati Neutron Generator: end of LHC phase I
 - 10 APDs at ENEA reactor Tapiro: mid of HL-LHC.
 - Further exposure next week: beyond 3000 fb^{-1}
- Test bench in Rome1
 - APDs still operable
 - Parameters for ECAL barrel cooling + faster shaping time (new VFE) to mitigate dark current being clarified



GEM Background studies

PAVIA A. Magnani C. Riccardi P. Salvini I.Vai P.Vitulo, P. Montagna A. Braghieri

Testing GE1/1 and new MPGD at gamma, neutron irradiation facilities (GIF, Louvain, Uppsala) to study the response of MPGD, necessary to understand their behavior and operation in presence of large backgrounds. Simulations with Geant4

Requirements: suitable flux, proper location taking into account the detector dimensions, gas, HV

Facilities: BTF (1 MeV) (possibly), Louvain la Neuve (BE) → neutrons up to 50 MeV (peak 20 MeV) (**2014**)

Uppsala (SE) → neutrons from 20 MeV up to 175 MeV (quasi monoenergetic beams) (2015), GIF (Cern) → 662 keV gammas (2015)

FUNDS: Irradiation at Louvain la Neuve (BE)	7kE
Setup → Mechanics for support + transports	2kE
10x10 cm ² prototype chamber	3kE
receiver boards and test readout setup	3kE

ME at Louvain (0.25mu x4) 4kE

ME at Cern in order to prepare the setup (0.25mu x4) 4kE

New

Additional request total for 2014: 15kE + 8kE ME